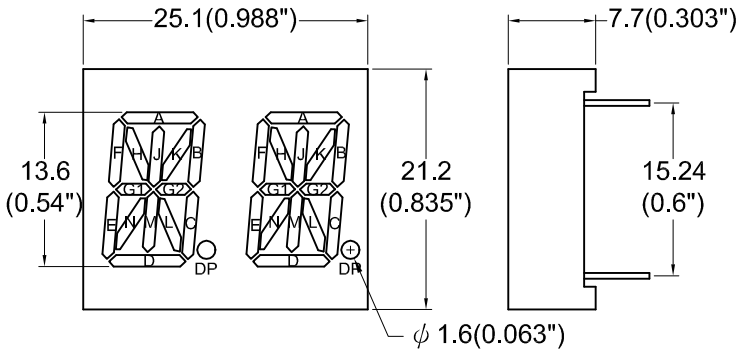


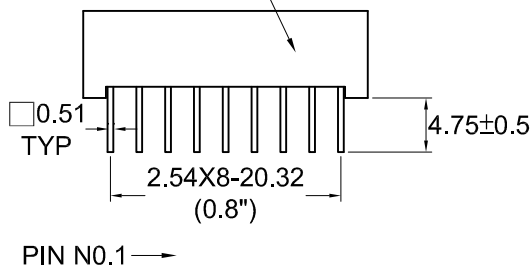


PACKAGE DIMENSION

INTERNAL CIRCUIT DIAGRAM

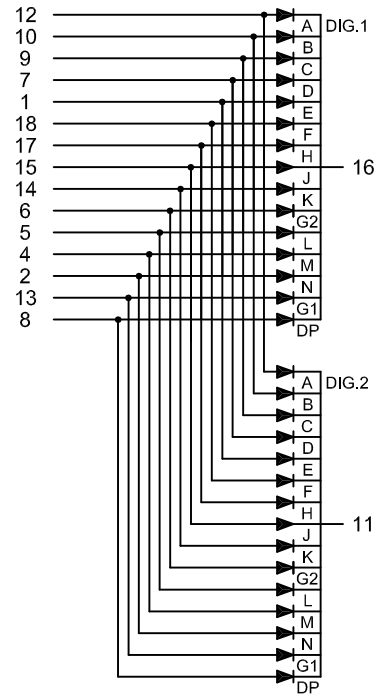


LDD525X-XX
LIGITEK



NOTE:1.All Dimension Are In Millimeters And (Inch)
 Tolerance Is ±0.25(0.01") unless Otherwise Noted
 2.Specifications are subject to change without notice.

LDD525X-XX



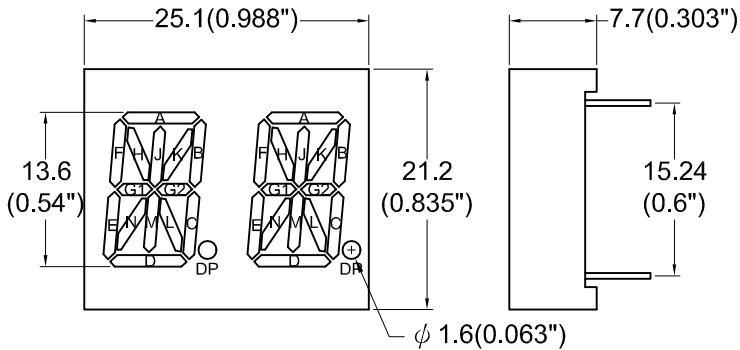
▪ Connection To Electrical Schematic

Electrical connection

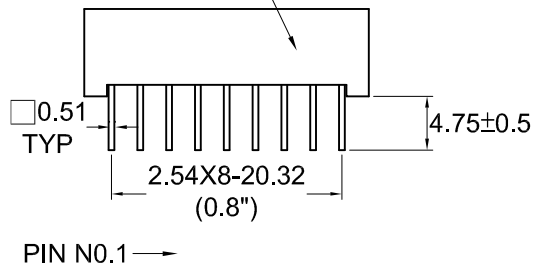
PIN NO.	LDD525X-XX	PIN NO.	
1	Anode E	13	Anode G1
2	Anode N	14	Anode K
3	NC	15	Anode J
4	Anode M	16	Common Cathode Dig.1
5	Anode L	17	Anode H
6	Anode G2	18	Anode F
7	Anode D		
8	Anode DP		
9	Anode C		
10	Anode B		
11	Common Cathode Dig.2		
12	Anode A		

PACKAGE DIMENSION

INTERNAL CIRCUIT DIAGRAM

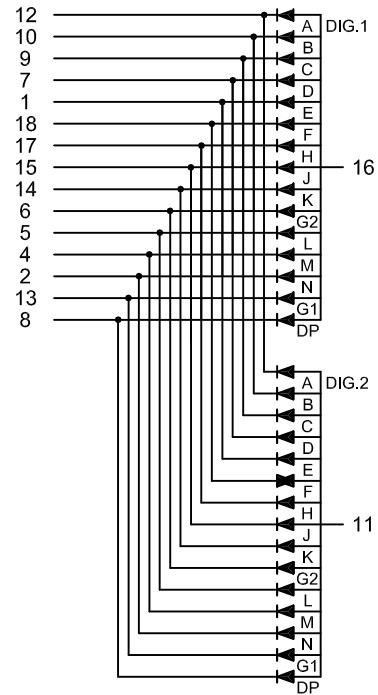


LDD526X-XX
LIGITEK



NOTE:1.All Dimension Are In Millimeters And (Inch)
Tolerance Is $\pm 0.25(0.01)$ " unless Otherwise Noted
2.Specifications are subject to change without notice.

LDD526X-XX



▪ Connection To Electrical Schematic

Electrical connection

PIN NO.	LDD526X-XX	PIN NO.	
1	Cathode E	13	Cathode G1
2	Cathode N	14	Cathode K
3	NC	15	Cathode J
4	Cathode M	16	Common Anode Dig.1
5	Cathode L	17	Cathode H
6	Cathode G2	18	Cathode F
7	Cathode D		
8	Cathode DP		
9	Cathode C		
10	Cathode B		
11	Common Anode Dig.2		
12	Cathode A		

• Part Selection And Application Information(Ratings At 25°C Ambient)

PART NO	CHIP		common cathode or anode	λ_p (nm)	$\Delta\lambda$ (nm)	Electrical					IV-M
	material	emitted				Vf(v)			Iv(mcd)		
						Min	Typ	Max	Min	Typ	
LDD5255-XX	GaAlAs	Red	Common Cathode	660	20	1.5	1.7	2.4	3.05	5.0	2:1
LDD5251-XX	GaP	Red		697	90	1.7	2.1	2.8	0.35	0.8	2:1
LDD5252-XX	GaP	Green		565	30	1.7	2.1	2.8	1.35	2.8	2:1
LDD5252V-XX	GaP	Green		565	30	1.7	2.1	2.8	1.75	3.05	2:1
LDD5254-XX	GaAsP/GaP	Orange		635	45	1.7	2.0	2.8	1.75	3.0	2:1
LDD5265-XX	GaAlAs	Red	Common Anode	660	20	1.5	1.7	2.4	3.05	5.0	2:1
LDD5261-XX	GaP	Red		697	90	1.7	2.1	2.8	0.35	0.8	2:1
LDD5262-XX	GaP	Green		565	30	1.7	2.1	2.8	1.35	2.8	2:1
LDD5262V-XX	GaP	Green		565	30	1.7	2.1	2.8	1.75	3.05	2:1
LDD5264-XX	GaAsP/GaP	Orange		635	45	1.7	2.0	2.8	1.75	3.0	2:1

▪ Absolute Maximum Rating (Ta=25 °C)

Parameter	Red		Green		Yellow		Orange		Unit	Remark
Forward Current Per Chip	SR	H	VG	G				E		
	40	15	30	30				30	mA	
Peak Current Per Chip (Duty 1/10,0.1mS Pulse Width)	200	60	120	120				120	mA	
Power Dissipation Per Chip	110	45	100				100		mW	
Derating Linear From 25°C Per Chip	0.45	0.25	0.45				0.45		mA/°C	
Reverse Current Per Any Chip	10		10				10		μ A	
Operating Temperature	-25°C TO +85°C									
Storage Temperature	-25°C TO +85°C									

Solder Temperature 1-16 Inch Below Seating Plane For 3 Seconds At 260 °C

▪ Test Condition For Each Parameter

Parameter	Symbol	Unit	Test Condition
Forward Voltage Per Chip	Vf	volt	If=20mA
Luminous Intensity Per Chip	Iv	mcd	If=10mA
Peak Emission Wavelength	λ_p	nm	If=20mA
Spectral Line Half-Width	$\Delta\lambda$	nm	If=20mA
Reverse Current Any Chip	Ir	μ A	Vr=5V
Luminous Intensity Matching Ratio	IV-M		